

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6	("5128831" "6421711" "6441314").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 16:22
L10	16	("5012323" "5121293" "5128831" "5189505" "5289337" "5291061" "5323060" "5385869" "5422435" "5434745" "5474957" "5495398" "5513076" "5607099" "5963430" "6020629").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 18:02
L11	95	("5434745").URPN.	USPAT	OR	ON	2006/02/03 18:03
L12	109	("4288841" "4398235" "4551746" "4884237" "4956694" "4983533" "4996587" "5019943" "5036431" "5043794" "5128831" "5165067" "5222014" "5247423").PN. OR ("5434745").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 18:03
L20	55	("4143456" "4264917" "4300153" "4323914" "4358552" "4507675" "4642671" "4801998" "4862245" "4931852" "4961107" "4984059" "5051275" "5101465" "5108955" "5111278" "5144747" "5173764" "5184208" "5194930" "5218759" "5241456" "5252853" "5280192" "5286679" "5304842" "5311060" "5344795" "5379186" "5394303" "5434105" "5436203" "5440169" "5441684" "5450283" "5461255" "5488254" "5489538" "5489801" "5552635" "5598034" "5604376" "5641997" "5652461" "5656857" "5659952" "5701233" "5754408" "5866953" "6013948" "6188127" "6297548" "6313522" "6501165" "6650007").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 18:05
L21	52	("4574331" "4581675" "4764846" "5007841" "5027191" "5043794" "5241456" "5376825" "5432681").PN. OR ("5701233"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 18:08

L22	57	("3770529" "3852877" "4080513" "4188513" "4417413" "4663215" "4677528" "4770922" "4829666" "4871608" "4897918" "4964019" "5116440" "5139851" "5139852" "5274701" "5346750" "5384689" "5386343" "5396034" "5468999" "5481795" "5484647" "5506448" "5541450" "5550403" "5558928" "5562971" "5578796" "5583376" "5600541" "5616888" "5628919" "5635301" "5646828" "5650918" "5701233" "5719438" "5729894" "5731227" "5763947" "5972482" "6029343").PN. OR ("6324067"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 19:51
L23	1	"6201707".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 19:51
L24	0	(board pcb bga) with photolithography with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L25	37	(board pcb bga) with photolithography with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L26	143	(board pcb bga) with opening with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L27	4	(board pcb bga) with opening with (arcrylic urethane polyimide)same ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L28	22	(board pcb bga substrate) with opening with (arcrylic urethane polyimide)same ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L29	939	(board pcb bga substrate) with (arcrylic urethane polyimide)same ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14

L30	166	(board pcb bga substrate) with (arcrylic urethane polyimide)same ground and photolithography	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L31	117	(board pcb bga substrate) with (arcrylic urethane polyimide)same ground and photolithography	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L32	32	("3798762" "3846166" "4250616" "4299873" "4434544" "4522667" "4624896" "4740414" "4806188" "4816323" "4830691").PN. OR ("5337466").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L33	103817	"174"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L34	0	L33 and ground with photolithography with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L35	0	L33 and photolithography with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L36	43	L33 and photolithography with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L37	117	L33 and photolithography same (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L38	74	L37 not L36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L39	0	("2002/0195272").URPN.	USPAT	OR	ON	2006/02/03 20:14
L40	0	("2002/0195272").URPN.	USPAT	OR	ON	2006/02/03 20:14
L41	0	("2002/0195272").URPN.	USPAT	OR	ON	2006/02/03 20:14

L42	0	("2002/0195272").URPN.	USPAT	OR	ON	2006/02/03 20:14
L43	1	"6441314".pn.	USPAT	OR	ON	2006/02/03 20:14
L44	28	("3471631" "5055321" "5321210" "5322593" "5337466" "5426849" "5519177" "5590461" "5628852" "5686702" "5741575" "5745984" "5956843" "6049123" "6127633" "6214641" "6217987" "6248428" "6251502" "6261671" "6274821").PN. OR ("6441314"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L45	8245	stacked with substrate with (IC chip die semiconductor wafer)	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L46	154	stacked with pcb with (IC chip die semiconductor wafer)	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L47	32	("3105869" "4473263" "5019943" "5239447" "5490324" "5506448" "5783870" "5801438" "5963429" "6049467" "6093029" "6109929" "6154371" "6157541" "6163070" "6169325" "6181002" "6294406" "6310392" "6313522" "6324067" "6353263" "6365963" "6369448" "6384473" "6407456" "6418033" "6420782" "6445591" "6472744").PN. OR ("6777794"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L48	55	("5012323" "5121293" "5128831" "5189505" "5289337" "5291061" "5323060" "5385869" "5422435" "5434745" "5474957" "5495398" "5513076" "5607099" "5963430" "6020629").PN. OR ("6313522"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L49	15	("5963430").URPN.	USPAT	OR	ON	2006/02/03 20:14
L50	18	("5099309" "5579207" "5642265").PN. OR ("5963430"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L51	2	("3879840" "5059553").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L52	37	("3716907" "4205099" "4263606" "4970571").PN. OR ("5059553"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L53	27	("3096262" "3495324" "3669734" "3760238").PN. OR ("4205099"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L54	25767	conductive near3 oxide	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L55	574072	conductive near3 oxide adn semiconductor	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14

L56	14309	conductive near3 oxide and semiconductor	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L57	8457	L56 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L58	1	"4575700".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L59	50	low adj loss adj dielectric near3 oxide	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L60	7	low adj loss near4 oxide and wave adj guide	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L61	93	low adj loss near4 oxide and wave\$3guide	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L62	33	coplanar with waveguide same insulating with oxide	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L63	2	"4575700".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L64	1	1986-087967.NRAN.	DERWENT	OR	ON	2006/02/03 20:14
L65	12	("3891949" "3982271" "4379307").PN. OR ("4575700").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L66	9	("4575700").URPN.	USPAT	OR	ON	2006/02/03 20:14
L67	0	coplanar with waveguide with oxid	USPAT	OR	ON	2006/02/03 20:14
L68	8	coplanar with waveguide with oxide	USPAT	OR	ON	2006/02/03 20:14
L69	10	coplanar with waveguide with oxide	USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/03 20:14
L70	4	coplanar with waveguide same silicon adj oxide	USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/03 20:14
L71	2	"20050121769".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14

L72	17	("5012323" "5121293" "5128831" "5189505" "5289337" "5291061" "5323060" "5385869" "5422435" "5434745" "5474957" "5495398" "5513076" "5607099" "5784260" "6020629" "6313522").PN. OR ("6603198").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L73	14	("3764856" "3829601" "3904934" "4574331" "4581679" "4764846" "4773868" "4833568" "4894706" "4983533" "4988306" "5007841" "5019945" "5030110").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L74	14	("3764856" "3829601" "3904934" "4574331" "4581679" "4764846" "4773868" "4833568" "4894706" "4983533" "4988306" "5007841" "5019945" "5030110").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L75	208	("3764856" "3829601" "3904934" "4574331" "4581679" "4764846" "4773868" "4833568" "4894706" "4983533" "4988306" "5007841" "5019945" "5030110").PN. OR ("5128831").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L76	0	stacking with IC adj packages near increase	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L77	2	stack\$3 with IC adj packages near increase	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L78	110	"www.altavista.com"	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L79	32	"RF transceiver" and (package with (semiconductor IC integrated adj circuit silicon die chip wafer)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L80	291	"transceiver" and (package with (semiconductor IC integrated adj circuit silicon die chip wafer)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L81	93	"transceiver" and (package with (semiconductor IC integrated adj circuit silicon die chip wafer)).ab.	USPAT	OR	ON	2006/02/03 20:14
L82	82	L81 not L79	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L83	27	"transceiver" with couple with chip	USPAT	OR	ON	2006/02/03 20:14
L84	7	"transceiver" with improve with chip	USPAT	OR	ON	2006/02/03 20:14

L85	180	"transceiver" with wireless with chip	USPAT	OR	ON	2006/02/03 20:14
L86	8	"transceiver" with wireless with remote with (IC CHIP DIE WAFER)	USPAT	OR	ON	2006/02/03 20:14
L87	1571	(257/698).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:14
L88	2064	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:14
L89	485	(257/688).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:14
L90	3973	L87 L88 L89	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L91	0	L90 and (board pcb bga) with opening with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L92	182	L90 and (board pcb bga substrate) and photolithography	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L93	0	(board pcb bga) with photolithography with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L94	939	(board pcb bga substrate) with (arcrylic urethane polyimide)same ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L95	103817	"174"\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14

L96	0	L95 and ground with photolithography with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L97	0	L95 and photolithography with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L98	117	L95 and photolithography same (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L99	0	("2002/0195272").URPN.	USPAT	OR	ON	2006/02/03 20:14
L100	0	("2002/0195272").URPN.	USPAT	OR	ON	2006/02/03 20:14
L101	0	("2002/0195272").URPN.	USPAT	OR	ON	2006/02/03 20:14
L102	0	("2002/0195272").URPN.	USPAT	OR	ON	2006/02/03 20:14
L103	8245	stacked with substrate with (IC chip die semiconductor wafer)	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L104	25767	conductive near3 oxide	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L105	574072	conductive near3 oxide adn semiconductor	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L106	14309	conductive near3 oxide and semiconductor	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L107	12	("3891949" "3982271" "4379307").PN. OR ("4575700").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L108	0	coplanar with waveguide with oxid	USPAT	OR	ON	2006/02/03 20:14
L109	8	coplanar with waveguide with oxide	USPAT	OR	ON	2006/02/03 20:14
L110	0	stacking with IC adj packages near increase	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L111	110	"www.altavista.com"	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L112	291	"transceiver" and (package with (semiconductor IC integrated adj circuit silicon die chip wafer)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14

L113	93	"transceiver" and (package with (semiconductor IC integrated adj circuit silicon die chip wafer)).ab.	USPAT	OR	ON	2006/02/03 20:14
L114	1571	(257/698).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:14
L115	2064	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:14
L116	485	(257/688).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/03 20:14
L117	3973	L114 L115 L116	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L118	0	L117 and (board pcb bga) with opening with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L119	1	"6441314".pn.	USPAT	OR	ON	2006/02/03 20:14
L120	1	"4575700".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L121	1	1986-087967.NRAN.	DERWENT	OR	ON	2006/02/03 20:14
L122	37	(board pcb bga) with photoli\$9 with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L123	4	(board pcb bga) with opening with (arcrylic urethane polyimide)same ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L124	22	(board pcb bga substrate) with opening with (arcrylic urethane polyimide)same ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14

L125	32	("3798762" "3846166" "4250616" "4299873" "4434544" "4522667" "4624896" "4740414" "4806188" "4816323" "4830691").PN. OR ("5337466").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L126	43	L95 and photolithography with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L127	74	L98 not L126	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L128	28	("3471631" "5055321" "5321210" "5322593" "5337466" "5426849" "5519177" "5590461" "5628852" "5686702" "5741575" "5745984" "5956843" "6049123" "6127633" "6214641" "6217987" "6248428" "6251502" "6261671" "6274821").PN. OR ("6441314"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L129	32	("3105869" "4473263" "5019943" "5239447" "5490324" "5506448" "5783870" "5801438" "5963429" "6049467" "6093029" "6109929" "6154371" "6157541" "6163070" "6169325" "6181002" "6294406" "6310392" "6313522" "6324067" "6353263" "6365963" "6369448" "6384473" "6407456" "6418033" "6420782" "6445591" "6472744").PN. OR ("6777794"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L130	55	("5012323" "5121293" "5128831" "5189505" "5289337" "5291061" "5323060" "5385869" "5422435" "5434745" "5474957" "5495398" "5513076" "5607099" "5963430" "6020629").PN. OR ("6313522"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L131	15	("5963430").URPN.	USPAT	OR	ON	2006/02/03 20:14
L132	18	("5099309" "5579207" "5642265").PN. OR ("5963430"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L133	2	("3879840" "5059553").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L134	37	("3716907" "4205099" "4263606" "4970571").PN. OR ("5059553"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14

L135	27	("3096262" "3495324" "3669734" "3760238").PN. OR ("4205099").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L136	50	low adj loss adj dielectric near3 oxide	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L137	7	low adj loss near4 oxide and wave adj guide	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L138	93	low adj loss near4 oxide and wave\$3guide	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L139	33	coplanar with waveguide same insulating with oxide	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L140	2	"4575700".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L141	9	("4575700").URPN.	USPAT	OR	ON	2006/02/03 20:14
L142	10	coplanar with waveguide with oxide	USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/03 20:14
L143	4	coplanar with waveguide same silicon adj oxide	USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/03 20:14
L144	2	"20050121769".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L145	17	("5012323" "5121293" "5128831" "5189505" "5289337" "5291061" "5323060" "5385869" "5422435" "5434745" "5474957" "5495398" "5513076" "5607099" "5784260" "6020629" "6313522").PN. OR ("6603198").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L146	14	("3764856" "3829601" "3904934" "4574331" "4581679" "4764846" "4773868" "4833568" "4894706" "4983533" "4988306" "5007841" "5019945" "5030110").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L147	14	("3764856" "3829601" "3904934" "4574331" "4581679" "4764846" "4773868" "4833568" "4894706" "4983533" "4988306" "5007841" "5019945" "5030110").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14

L148	2	stack\$3 with IC adj packages near increase	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L149	32	"RF transceiver" and (package with (semiconductor IC integrated adj circuit silicon die chip wafer)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L150	82	L113 not L149	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L151	27	"transceiver" with couple with chip	USPAT	OR	ON	2006/02/03 20:14
L152	7	"transceiver" with improve with chip	USPAT	OR	ON	2006/02/03 20:14
L153	8	"transceiver" with wireless with remote with (IC CHIP DIE WAFER)	USPAT	OR	ON	2006/02/03 20:14
L154	143	(board pcb bga) with opening with (arcrylic urethane polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L155	166	(board pcb bga substrate) with (arcrylic urethane polyimide)same ground and photolithography	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L156	117	(board pcb bga substrate) with (arcrylic urethane polyimide)same ground and photolithography	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L157	154	stacked with pcb with (IC chip die semiconductor wafer)	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L158	208	("3764856" "3829601" "3904934" "4574331" "4581679" "4764846" "4773868" "4833568" "4894706" "4983533" "4988306" "5007841" "5019945" "5030110").PN. OR ("5128831").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14
L159	180	"transceiver" with wireless with chip	USPAT	OR	ON	2006/02/03 20:14
L160	182	L117 and (board pcb bga substrate) and photolithography	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/03 20:14
L161	8457	L106 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 20:14